Application Note #3-31-14-A

ConnectCore™ 6

Carrier Board Routing Pattern Guidelines

Placement sensitive components that require close proximity to the Freescale i.MX6 application processor are populated on the bottom side of the ConnectCore 6 module PCB.

In order to accommodate those components, the carrier (host) board needs to provide a simple and small routing pattern opening of 16.5 mm (0.6496") x 16.75 mm (0.6594") in the ConnectCore 6 module placement area.

NOTE: The opening of the routing pattern also offers customers with high-end/high-load multi core applications with an option to place thermal pad/paste directly underneath the Freescale i.MX6 application processor for efficient heat dissipation.

The minimum thickness of the carrier board is 0.9 mm (0.0354") to compensate for the maximum height of the components populated on the bottom side of the ConnectCore 6 module PCB.

Please refer to the attached archive file (P/N 96000669_A.ZIP), which includes reference drawings (96000669-A-PDF.PDF) and a corresponding DXF file (96000669-A-DXF.DXF).

In addition, the design files of the ConnectCore 6 development board / SBC also provide a routing pattern reference implementation for customers.

Please visit the Digi technical support site to access the most current design documentation.

Document Change Log

Revision	Date	Comments
A	3-31-2014	Initial

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